MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ODCSP54 5.263x5.072
CASE 570BS
ISSUE A

DATE 21 OCT 2019

NOTES:
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CRINGS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CRINGS OF THE SOLDER BALLS.
6. GLASS: 0.405 [mm] THICKNESS, REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.044 [mm] THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS +/-1°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL FOIL ARRAY DIMENSIONS.
11. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.441, -0.129).
12. PACKAGE CENTER (X, Y) = (0.000, 0.000).

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